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1. Style

This specification describes Snap-Acting Pushbutton Switches, mainly used as signal switch of electric devices, with the general requirements of mechanical and electrical characteristic.

Operating Temperature Range : -30 $^{\circ}\text{C} \text{-+85}^{\circ}\text{C}\text{.}$

2. Contact Rating:

2.1 Silver Plating Standard:

Plating		Rating
Silver	Fixed Terminal: Silver plated over copper alloy. Movable contact: Silver plated over copper alloy.	
Gold over silver	Fixed Terminal: Copper alloy with silver plated over gold plate. Movable contact: Copper alloy with silver plated over gold plate.	3Amps @120VAC or
Silver, tin-lead	Fixed Terminal: Copper alloy with silver plated ,tin-lead. Movable contact: Silver plated over copper alloy.	28VDC. 1Amps @250VAC.
Gold over silver tin-lead	Fixed Terminal: Copper alloy with silver plated over gold plate, tin-lead. Movable contact: Copper alloy with silver plated over gold plate.	



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2.2 Gold Plating Standard:

Plating		Rating
Gold	Fixed Terminal: Copper alloy with gold plate over nickel plate. Movable contact: Copper alloy with gold	
	plate over nickel plate.	0.4 VA Max. @20VAC or DC
Gold,tin-lead	Fixed Terminal: Copper alloy with gold plated over nickel plate, tin-lead.	Max.
Gora, cili-leda	Movable contact: Copper alloy with gold plated over nickel plate.	

3.Type of Actuation: Snap-Acting Pushbutton Switches.

4. Test Sequence:

	ITEM	DESCRIPTION	TEST CONDITIONS	REQUIREMENTS
	1		By Visual Examination check without and out pressure & testing.	There shall be no defects that affect the serviceability of the product.
ELECTRIC F	2	Contact Resistance	<pre>@2-4VDC 100mA. For both silver and gold plated contacts.</pre>	20mΩ Max
PERFORMANCE	3	Insulation Resistance	Measurements shall be made following application of 1000 V/DC 100mA potential across terminals and cover.	1000MΩ min/1000V
	4	Dielectric Withstanding Voltage	1000 VAC(50Hz or 60Hz) shall be applied across terminals and cover for 1 minute.	



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	ITFM	DESCRIPTION	TEST CONDITIONS	REQUIREMENTS
	5		Through Hole Type ■WAVE SOLDERING: ①Soldering Temperature:260±5°C. ②Duration of Solder Immersion: 5 ±1	①Shall be free from pronounced backlash and falling-off or breakage terminals. ②As shown in item 2~4.
MECHANICAL PERFPRMANCE	6	Vibration	Shall be vibrated in accordance with Method 201A of MIL-STD-202F ①Frequency: 10-55-10Hz in 1-min/cycle. ②Direction: 3 vertical directions including the directions of operation ③Test time:2 hours each direction.	As shown in itom 2.4
NCE	7	Shock	Shall be shocked in accordance with Method 213B condition A of MIL-STD-202F ①Acceleration; 5kg ②Action time: 11±1m seconds. ③Testing Direction: 6 sides. ④Test Cycle: 3 times in each direction.	As shown in item 2~4
	8	Actuation Force	<pre>①MODEL-1305N MECHANICAL TEST 500gram \ 1000gram \ 2000gram. ②Stroke: 1.0±0.2mm</pre>	①At for test the force. Force:300±100grams. ②Stroke:1.0±0.2mm
OPERATING LIFE	9	Operating Life	Measurements shall be made following the test forth below: ①3A,120VAC resistive load—silver plated. 1A,250VAC resistive load—silver plated 0.4A, 20VAC resistive load—gold plated. ② Rate of Operation: 6-8operation cycles per minute. ③ Electronics Life Test: 6,000 cycles.	1000V.
			Mechanical Life Test: 50,000 cycles.	Contact Resistance: $20m\Omega$ Max.



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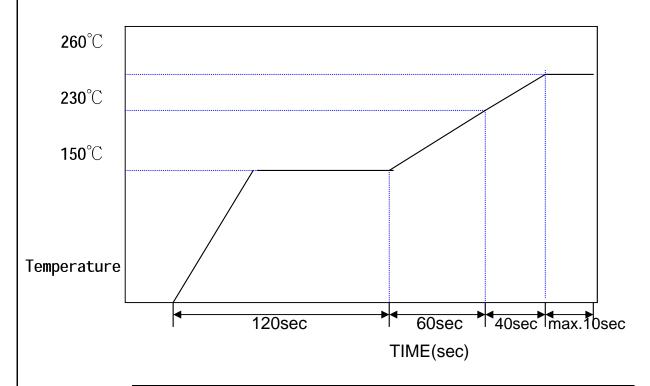
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	ITEM	DESCRIPTION	TEST CONDITIONS	REQUIREMENTS
	10	Resistance Low Temperature	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for 1 hour before the measurements are made: 0 Temperature: -40 ± 3 °C 0 Time: 96 hours.	
HUNIDI	11	Resistance High Temperature	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before the measurements are made: ①Temperature:85 ±2°C ②Time:96 hours.	① As shown in item 3~4.② Insulation Resistance: 1000MΩ.
HUMIDITY RESISTANCE	12	Resistance Humidity	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before the measurements are made:	_
	13	The Salt Testing	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before the measurements are made: ①Temperature:35±2°C ②The ratio of salt-water:5% ③The spray amout of salt- water: 1~2 ml/h. ④ Time:48 hours.	The testing standard based on bubble, crack, And magnifying glass with gauge.



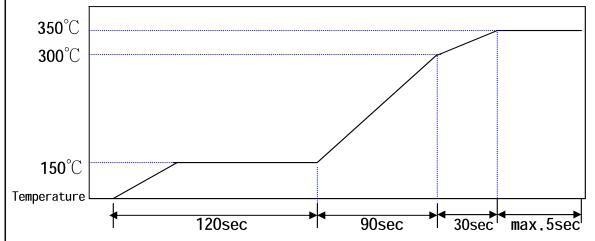
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5. SOLDERING CONDITIONS:



Soldering Temperature	Max.350°C
Continuous Soldering Time	Max. 5 seconds

■ Manual Soldering



■ Precautions in Handling

Care should be exercised so that flux from the upper part of the printed circuit board does not adhere to the switch.